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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Ajit V. SATHE

Serial No.: 09/893,466

Filed: 29 June 2001

For: ARRANGEMENTS TO PROVIDE MECHANICAL STIFFENING
ELEMENTS TO A THIN-CORE OR CORELESS SUBSTRATE

Art Unit: 2872

Examiner: Ishwarbhai B. Patel

AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

19 March 2003

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Sir:

In response to the Office Action having a USPTO mailing date of 19 December 2002, Applicant respectfully submits the following amendments and remarks in connection with the above-identified application.

IN THE CLAIMS:

Please enter the following clarified Claims 53-64.

53.(Once Amended) An electronic system as claimed in claim 52, the IC-PCB carrier package being one of a flip chip pin grid array (FC-PGA) and a flip chip ball grid array (FC-BGA) carrier package.

54.(Once Amended) An electronic system as claimed in claim 52, where the stiffener is substantially made of at least one of a metal, plastic, glass and ceramic material, is one of a molded, stamped, etched, extruded and deposited stiffener, and